

Notice of References Cited	Application/Control No. 09/915,145	Applicant(s)/Patent Under Reexamination NOGAMI ET AL.	
	Examiner Thomas J. Magee	Art Unit 2811	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-5,695,810	12-1997	Valery M. Dubin et al.	427/96
	C	US-			
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	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Syd R. Wilson, Clarence J. Tracy, and John L. Freeman, Jr., "Handbook of Multilevel Metallization for Integrated Circuits," Noyes Publ., Westwood, New Jersey, (1993), p.44, 428.
	V	Y. Shacham-Diamand and S.Y. Lopatin, "High Aspect Ratio Quarter-Micron Electroless Copper Integrated Technology," Proc. Materials for Advanced Metallization (Europe) (1997), pp. 11 - 14.
	W	Arthur Sherman, "Chemical Vapor Deposition for Microelectronics," Noyes Publ., EWestwood, New Jersey, (1987) pp.66-67.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.